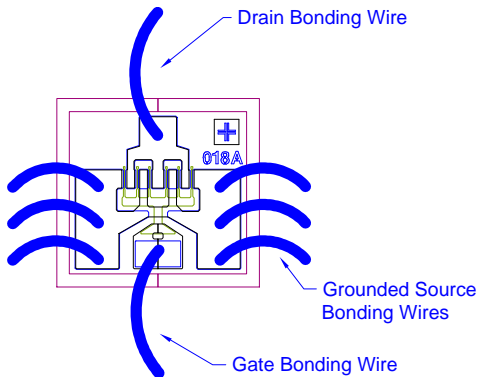
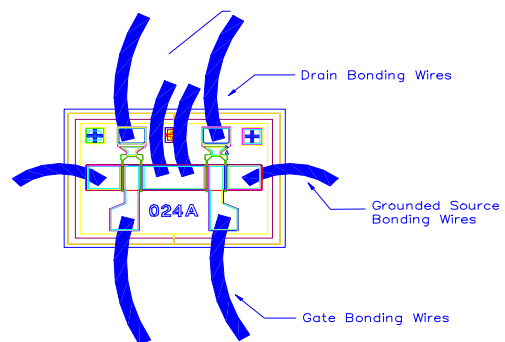


**Recommended Wire Bonding
For Excelics FETs**

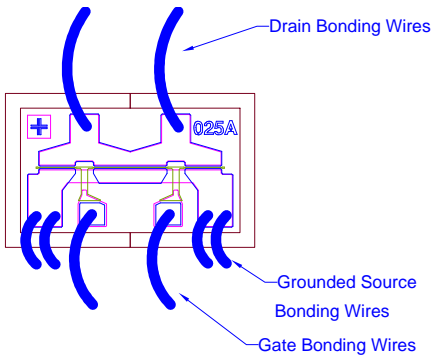
E018A



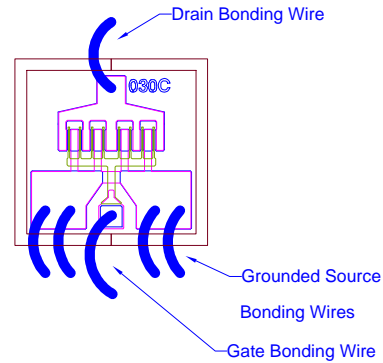
E024A



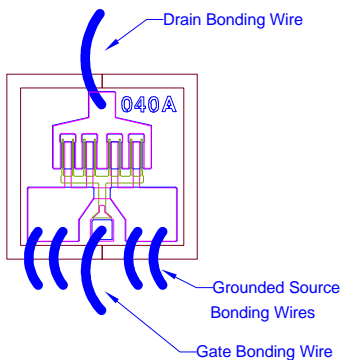
E025A



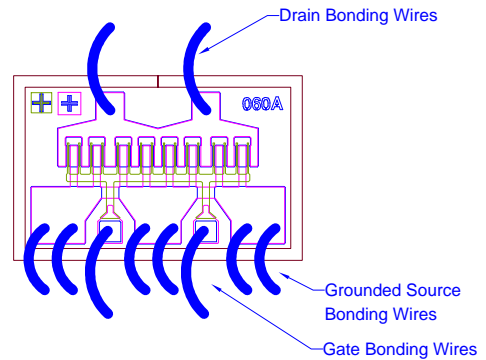
E030C



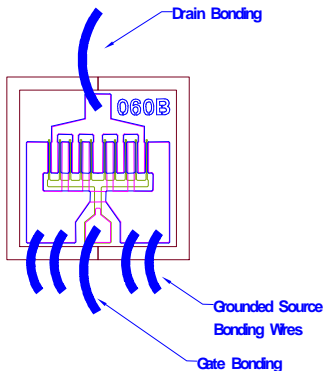
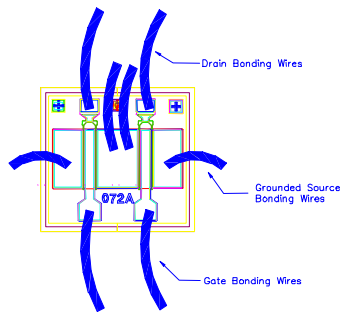
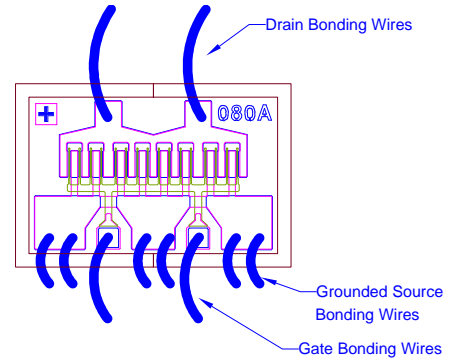
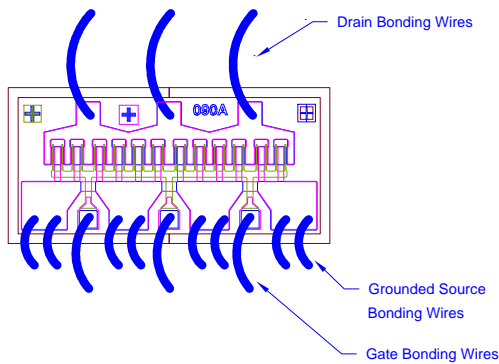
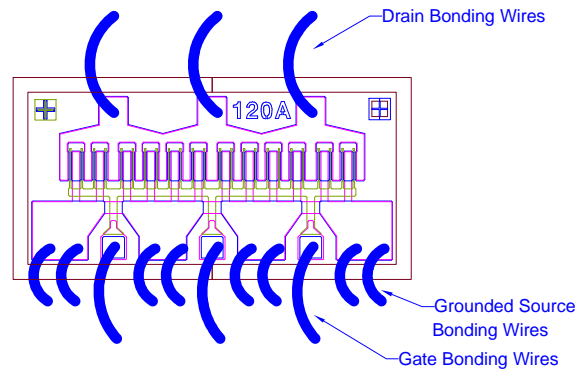
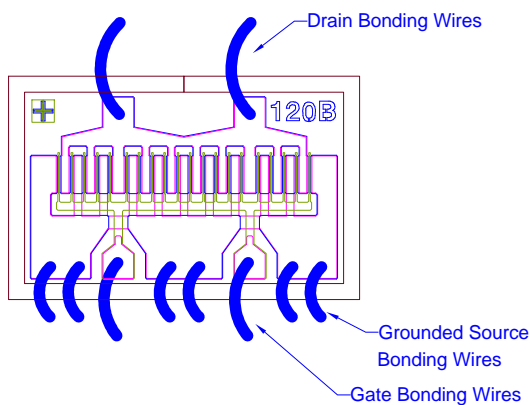
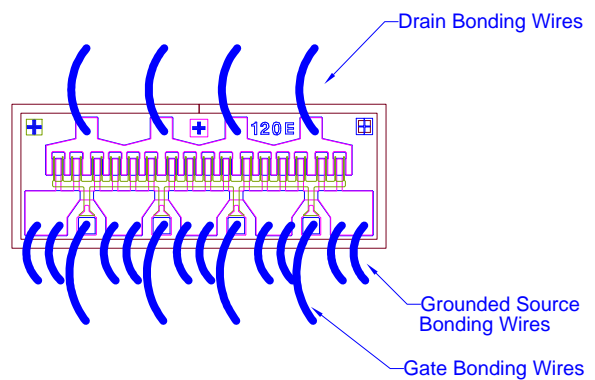
E040A



E060A

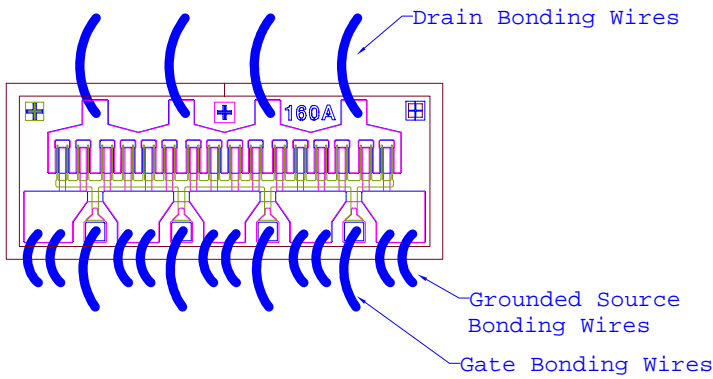


Note: 1.) For E240D, E480C, E720A, E960B and E1200A, 0.7 or 1 mils diameter Au wires can be used for bonding source and gate pads. However, 1 mils diameter Au wires (or 2 x 0.7 mils Au wires) should be used for bounding drain pads. 2.) For the rest of devices, 0.7 or 1 mils diameter Au wires can be used for bonding source and drain pads. However, for bonding gate pads, 0.7 mils diameter Au wires should be used. 3.) For the devices with via holes (ENNNXV), no bond wires on source pads are required!

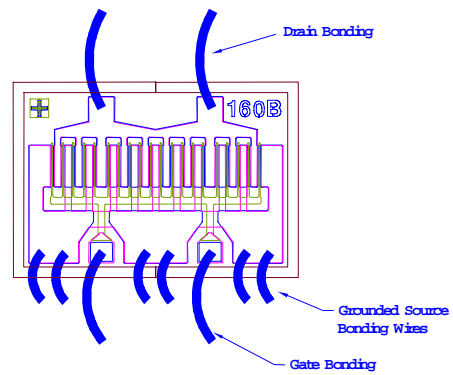
E060B**E072A****E080A****E090A****E120A****E120B****E120E**

Note: 1.) For E240D, E480C, E720A, E960B and E1200A, 0.7 or 1 mils diameter Au wires can be used for bonding source and gate pads. However, 1 mils diameter Au wires (or 2 x 0.7 mils Au wires) should be used for bounding drain pads. 2.) For the rest of devices, 0.7 or 1 mils diameter Au wires can be used for bonding source and drain pads. However, for bonding gate pads, 0.7 mils diameter Au wires should be used. 3.) For the devices with via holes (ENNNXV), no bond wires on source pads are required!

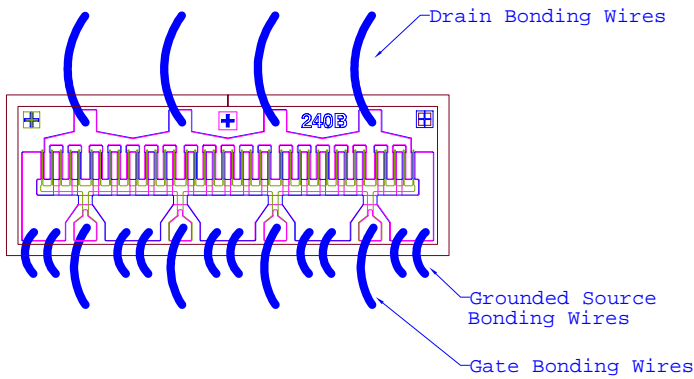
E160A



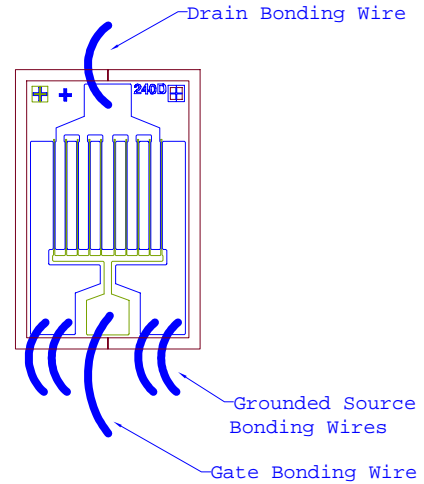
E160B



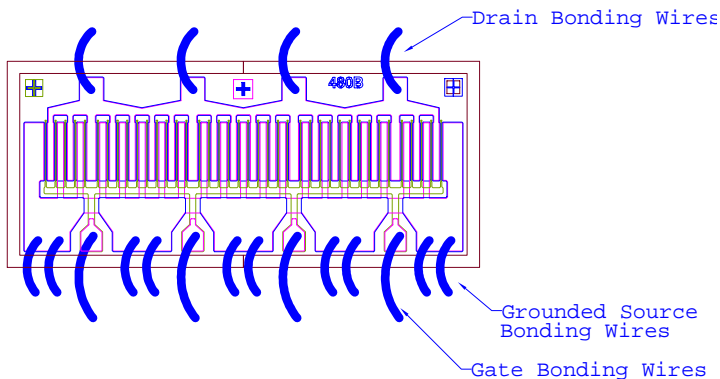
E240B



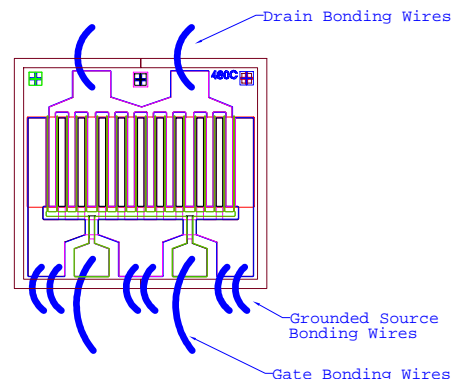
E240D



E480B

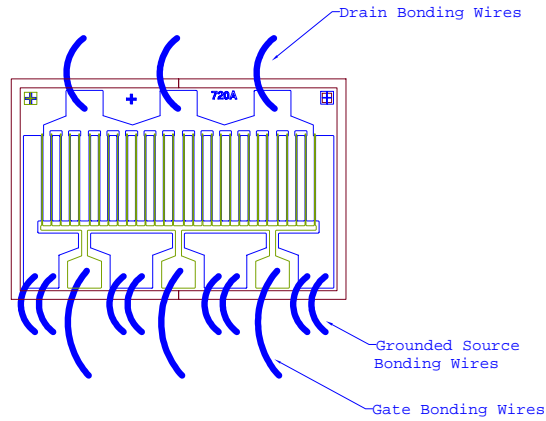


E480C

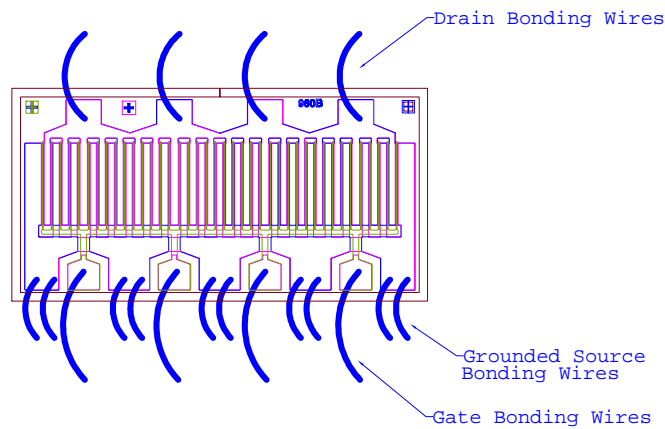


Note: 1.) For E240D, E480C, E720A, E960B and E1200A, 0.7 or 1 mils diameter Au wires can be used for bonding source and gate pads. However, 1 mils diameter Au wires (or 2 x 0.7 mils Au wires) should be used for bonding drain pads. 2.) For the rest of devices, 0.7 or 1 mils diameter Au wires can be used for bonding source and drain pads. However, for bonding gate pads, 0.7 mils diameter Au wires should be used. 3.) For the devices with via holes (ENNNXV), no bond wires on source pads are required!

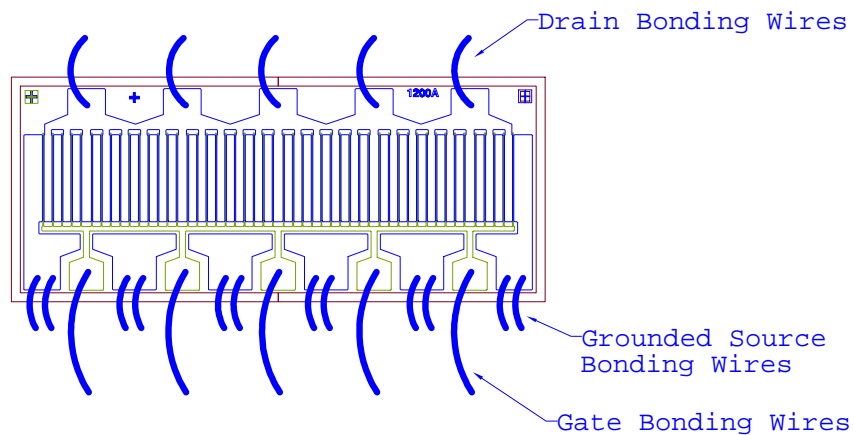
E720A



E960B



E1200A



Note: 1.) For E240D, E480C, E720A, E960B and E1200A, 0.7 or 1 mils diameter Au wires can be used for bonding source and gate pads. However, 1 mils diameter Au wires (or 2 x 0.7 mils Au wires) should be used for bonding drain pads. 2.) For the rest of devices, 0.7 or 1 mils diameter Au wires can be used for bonding source and drain pads. However, for bonding gate pads, 0.7 mils diameter Au wires should be used. 3.) For the devices with via holes (ENNNXV), no bond wires on source pads are required!